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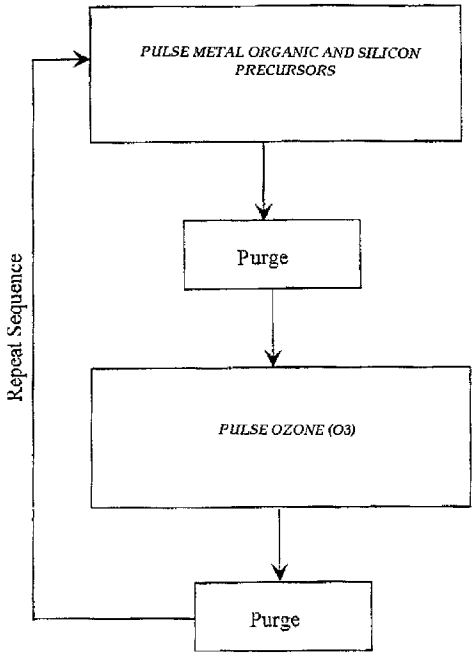
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(54) Title: ATOMIC LAYER DEPOSITION OF HIGH K METAL SILICATES



(57) Abstract: The present invention relates to the atomic layer deposition ("ALD") of high k dielectric layers of metal silicates, including hafnium silicate. More particularly, the present invention relates to the ALD formation of metal silicates using metal organic precursors, silicon organic precursors and ozone. Preferably, the metal organic precursor is a metal alkyl amide and the silicon organic precursor is a silicon alkyl amide.

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